



INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(51) International Patent Classification ⁶ : C09J 7/02, G09F 3/02	A1	(11) International Publication Number: WO 99/55791 (43) International Publication Date: 4 November 1999 (04.11.99)
(21) International Application Number: PCT/US99/03695 (22) International Filing Date: 19 February 1999 (19.02.99) (30) Priority Data: 09/067,250 27 April 1998 (27.04.98) US (71) Applicant: MINNESOTA MINING AND MANUFACTURING COMPANY [US/US]; 3M Center, P.O. Box 33427, Saint Paul, MN 55133-3427 (US). (72) Inventors: JUNG, Dieter; P.O. Box 33427, Saint Paul, MN 55133-3427 (US). LUDWIG, Pauline, E.; P.O. Box 33427, Saint Paul, MN 55133-3427 (US). (74) Agents: WEISS, Lucy, C. et al.; Minnesota Mining and Manufacturing Company, Office of Intellectual Property Counsel, P.O. Box 33427, Saint Paul, MN 55133-3427 (US).		(81) Designated States: AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, CA, CH, CN, CU, CZ, DE, DK, EE, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MD, MG, MK, MN, MW, MX, NO, NZ, PL, PT, RO, RU, SD, SE, SG, SI, SK, SL, TJ, TM, TR, TT, UA, UG, UZ, VN, YU, ZW, ARIPO patent (GH, GM, KE, LS, MW, SD, SZ, UG, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, GW, ML, MR, NE, SN, TD, TG). Published <i>With international search report.</i>

(54) Title: TAMPER-INDICATING ARTICLE FOR REUSABLE SUBSTRATES

(57) Abstract

A tamper-indicating article comprises (a) a pressure-sensitive adhesive film or pressure-sensitive adhesive-coated tape that can be removed, without exhibiting cohesive failure, from a substrate surface (e.g., an automobile windshield) by stretching the film or tape; and (b) at least one damageable layer that shows cohesive or intralayer failure when an attempt is made to remove the article from the substrate surface. The article is especially useful for application to valuable, non-disposable substrates and can be removed therefrom without substrate damage.

